

U.S. Corporate Headquarters 400 Valley Rd. Warrington, PA 18976 1(800) 523-2575 / (215) 343-6484 1(800)343-3291 fax info@polysciences.com Polysciences Europe GmbH Handelsstrasse 3 D-69214 Eppelheim, Germany +(49) 6221-765767 +(49) 6221-764620 fax info@polysciences.de Polysciences Asia-Pacific, Inc. 2F-1, 207 Tunhwa N. Rd. Taipei, Taiwan 10595 (886) 2 8712 0600 (886) 2 8712 2677 fax info@polysciences.tw

*No***SWEEP**[™] *Wire Bond Encapsulant*

TECHNICAL DATA SHEET 626

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DESCRIPTION

Polysciences, Inc. *No*SWEEPTM Wire Bond Encapsulant is a novel, 100% solids, one component, silica filled liquid encapsulant designed for encapsulation of very narrow diameter, long and ultra fine pitch wire bonds on semiconductor devices. *No*SWEEPTM is dispensed onto the wires immediately after wire bonding, flowing easily between and around the wires without causing sweep or sag and without voids. *No*SWEEPTM is quickly gelled with UV energy to lock the wires in place so the device can be handled and molded with no damage to the wires.

CUSTOMER BENEFITS

NoSWEEP™ Wire Encapsulant offers the following distinct advantages over conventional molding systems:

- Enables implementation of 35µm pitch roadmap wire bonding
- Allows for the use of longer wires with low cost, high density substrates and enables simple die shrinks
- Enables cost reduction through the use of thinner diameter gold wire
- Enhanced room temperature

UNCURED (WET) PROPERTIES

Color Off-white **Filler Content** 165%

Viscosity @ 25°C RVDV-II+, Spindle 14, Cup 6R)

250 kcps @ 0.5 rpm

Pot Life @ 45°C >24 hours Density 1.67 gram/cm3

PROCESS PARAMETERS

Dispensing Heat dispense needle to 60°C

Heat substrate to 90-100°C

Recommended Cure Cycle

UVA 1.0 Joules/cm $_2$ @ 90°C plus convection oven

130°C for 1 hour and 175°C for 3 hours

CURED PROPERTIES

Glass Transition Temp. (Tg) by DMA $174^{\circ}\mathrm{C}$

Coefficient of Thermal Expansion (CTE)

Alpha 1 = 23 ppm/ $^{\circ}$ C Alpha 2 = 63 ppm/ $^{\circ}$ C

Flexural Modulus (Three Point Bend)

9.0 GPA @ 25°C

Moisture Absorption after 192 hrs 30°C/60% RH 0.4%

Extractable Ionic Content (Na, K, CI, F) <10 ppm)

Dielectric Constant @ 1 MHz

N/A

Dielectric Strength v/mil @ 1/16"

N/A

STORAGE AND HANDLING

Shipping Recommended temperature is -10°C **Storage** Store at 5°C for up to 6 months

Safety Refer to MSDS for best handling practices.

All values are considered to be typical based on tests believed to be accurate. Polysciences, Inc. may change the data as appropriate.

North America (United States)

1 (800) 523-2575 / (215) 343-6484 1 (800) 343-3291 / (215) 343-0214 fax

Europe (Germany)

(49) 6221-765767 / (49) 6221-764620 fax

Asia-Pacific (Taiwan)

(886) 2 8712 0600 / (886) 2 8712 2677 fax

Online anytime at: polysciences.com

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